

LNPT[™] LUBRICOMP[™] COMPOUND DI001PXH

DI001PXH

DESCRIPTION

LNP LUBRICOMP DI001PXH compound is based on Polycarbonate (PC) resin containing silicone. Added features of this grade include: High Flow, Wear Resistant.

GENERAL INFORMATION	
Features	High Flow, Wear resistant, Healthcare/Formula lock, No PFAS intentionally added
Fillers	Unreinforced, Silicone
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Hygiene and Healthcare	Pharmaceutical Packaging and Drug Delivery, Surgical devices, General Healthcare, Patient Testing
Packaging	Industrial Packaging

TYPICAL PROPERTY VALUES

Revision 20241017

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yld, Type I, 5 mm/min	59	MPa	ASTM D638
Tensile Stress, brk, Type I, 5 mm/min	48	MPa	ASTM D638
Tensile Strain, yld, Type I, 5 mm/min	6.1	%	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	65	%	ASTM D638
Tensile Modulus, 5 mm/min	2220	MPa	ASTM D638
Flexural Strength, 1.3 mm/min, 50 mm span	89	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	2280	MPa	ASTM D790
Tensile Stress, yield, 5 mm/min	59	MPa	ISO 527
Tensile Stress, break, 5 mm/min	46	MPa	ISO 527
Tensile Strain, yield, 5 mm/min	5.9	%	ISO 527
Tensile Strain, break, 5 mm/min	26	%	ISO 527
Tensile Modulus, 1 mm/min	2210	MPa	ISO 527
Flexural Strength, 2 mm/min	83	MPa	ISO 178
Flexural Modulus, 2 mm/min	2170	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	NB	J/m	ASTM D4812
Izod Impact, notched, 23°C	285	J/m	ASTM D256
Instrumented Dart Impact Total Energy, 23°C	40	J	ASTM D3763
Izod Impact, unnotched 80*10*4 +23°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	45	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	125	°C	ASTM D648

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	124	°C	ISO 75 /Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.19	-	ASTM D792
Density	1.19	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.09	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.79	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.94	%	ASTM D955
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120	°C	
Drying Time	2 – 4	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	280 – 300	°C	
Nozzle Temperature	270 – 290	°C	
Front - Zone 3 Temperature	280 – 300	°C	
Middle - Zone 2 Temperature	270 – 290	°C	
Rear - Zone 1 Temperature	260 – 280	°C	
Hopper Temperature	60 – 80	°C	
Mold Temperature	80 – 100	°C	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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